

CLAIMS

What is claimed is:

1. A method of fabricating a microelectronic package, comprising:

providing a substrate;

providing a microelectronic die;

disposing a radiation curable material between said microelectronic die and said substrate surface;

exposing said substrate and said microelectronic die to radiation.
2. The method of claim 1, wherein exposing said substrate and said microelectronic die to radiation comprises exposing said substrate and said microelectronic die to said radiation substantially simultaneously with said disposing said radiation curable material between said microelectronic die and said substrate surface.
3. The method of claim 1, wherein disposing a radiation curable material comprises disposing an ultraviolet radiation curable material between said microelectronic die and said substrate surface.
4. The method of claim 3, wherein disposing an ultraviolet radiation curable material comprises disposing a material selected from the group consisting of epoxies, acrylates, silicones, urethane acrylates, cyanoacrylates, and bismaleimides.

5. The method of claim 1, wherein exposing said substrate and said microelectronic die to radiation comprises exposing said substrate and said microelectronic die to ultraviolet radiation.

6. A method of fabricating a microelectronic package, comprising:
providing a substrate having a surface and a plurality of lands disposed on said surface;
providing a microelectronic die having an active surface, at least one edge, and a plurality of pads disposed on said active surface in a corresponding relationship to said plurality of substrate lands;
electrically attaching said plurality of substrate lands to said plurality of corresponding microelectronic die pads with a plurality of conductive bumps;
disposing a radiation curable underfill material between said microelectronic die active surface and said substrate surface;
exposing said substrate and said microelectronic die to radiation.

7. The method of claim 6, wherein exposing said substrate and said microelectronic die to radiation comprises exposing said substrate and said microelectronic die to radiation substantially simultaneously with said disposing a radiation curable underfill material between said microelectronic die active surface and said substrate surface.

8. The method of claim 6, wherein disposing a radiation curable underfill material comprises disposing an ultraviolet radiation curable underfill material between said microelectronic die active surface and said substrate surface.

9. The method of claim 8, wherein disposing a radiation curable underfill material comprises disposing a material selected from the group consisting of epoxies, acrylates, silicones, urethane acrylates, cyanoacrylates, and bismaleimides.

10. The method of claim 6, wherein exposing said substrate and said microelectronic die to radiation comprises exposing said substrate and said microelectronic die to ultraviolet radiation.

11. The method of claim 6, further including attaching a back surface of a second microelectronic device to a back surface of said microelectronic die.

12. The method of claim 11, further including attaching at least one wirebond extending between at least one land on an active surface of said second microelectronic device and at least one wirebond land on said substrate.

13. A method of fabricating a microelectronic package, comprising:
providing a substrate having a surface and a plurality of lands disposed on said surface;
providing a microelectronic die having an active surface, an opposing back surface, and at least one land disposed on said microelectronic die active surface;
attaching said microelectronic die back surface to said substrate active surface with a radiation curable adhesive material; and
exposing said substrate and said microelectronic die to radiation.

14. The method of claim 13, wherein attaching said microelectronic die back surface to said substrate surface comprises disposing said radiation curable adhesive material on said substrate active surface and placing said microelectronic die back surface to said radiation curable adhesive material.

15. The method of claim 14, wherein attaching said microelectronic die back surface to said substrate surface comprises disposing an ultraviolet radiation curable adhesive material on said substrate active surface and placing said microelectronic die back surface to said ultraviolet radiation curable adhesive material.

16. The method of claim 13, wherein exposing said substrate and said microelectronic die to radiation comprises exposing said substrate and said microelectronic die to radiation substantially simultaneously with said attaching said microelectronic die back surface to said substrate active surface.

17. The method of claim 13, wherein disposing a radiation curable adhesive material comprises disposing an ultraviolet radiation curable adhesive material between said microelectronic die back surface and said substrate active surface.

18. The method of claim 17, wherein disposing a ultraviolet radiation curable adhesive material comprises disposing a material selected from the group consisting of epoxies, acrylates, silicones, urethane acrylates, cyanoacrylates, and bismaleimides.

19. The method of claim 13, wherein exposing said substrate and said microelectronic die to radiation comprises exposing said substrate and said microelectronic die to ultraviolet radiation.

20. The method of claim 13, further including attaching at least one wirebond extending between at least one land on said active surface microelectronic device and at least one wirebond land on said substrate.